

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
FU-CHANG HSU	07/22/2021
<b>RECEIVING PARTY DATA</b>	
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	10720215
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<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>SIGNATURE:</b>	/AlexaRay Martinez/
<b>DATE SIGNED:</b>	07/27/2021
<b>Total Attachments: 1</b>	
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PATENT

## ASSIGNMENT

WHEREAS, I, **Fu-Chang Hsu**, (hereinafter referred to as "ASSIGNOR"), am the inventor of United States Letters Patent No. **10,720,215**, issued on **July 21, 2020** for the invention entitled "**METHODS AND APPARATUS FOR WRITING NONVOLATILE 3D NAND FLASH MEMORY USING MULTIPLE-PAGE PROGRAMMING**";

WHEREAS, **NEO Semiconductor, Inc.**, a corporation organized and existing under the laws of the State of Delaware, having an address of **1871 The Alameda, Suite 250, San Jose, CA 95126** (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring my entire right, title and interest in and to the invention and said Letters Patent;

NOW THEREFORE, for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, said ASSIGNOR, has sold, assigned and set over, and by these presents does hereby sell, assign and set over unto the said ASSIGNEE, its legal representatives, successors and assigns, its entire rights, title and interest in and to said United States Letters Patent, and the invention disclosed, described or claimed in said Letters Patent, together with all divisions, reissues, continuations and extensions thereof, and any and all rights of recovery for past infringement of said Letters Patent.


I also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said patent and any applications throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and

I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

I hereby further agree that I will communicate to said ASSIGNEE, or its successors, assigns and legal representatives, any facts known to me respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

7/22/2021

Date



Fu-Chang Hsu